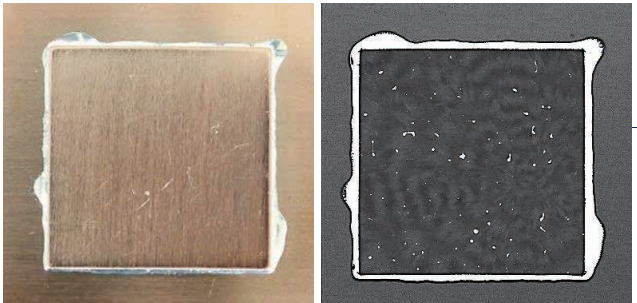


Lead-Free Solder Paste for Formic Acid Relow

# SN100C P900 D2



## SIGNIFICANT VOID REDUCTION



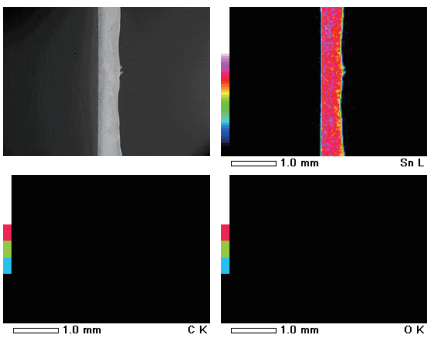
### Voiding Characteristics

Void observation method	Test component
X-ray transmission imaging	R3216 (Left) QFP (10mm) thermal land (Right)

In the manufacture of power semiconductors die attach in a formic acid atmosphere is being used increasingly because of the reduced incidence of voids in the solder joint. Voids reduce the heat transfer capacity of the solder joints, which can result in overheating of the die. SN100C P900 D2 solder paste has been formulated to deliver optimum performance in a formic acid atmosphere.

### Residue...

## NO RESIDUE



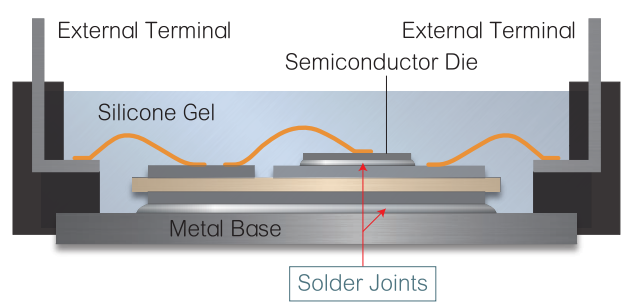
Observation method  
SEM-EDX analysis

Test material  
Copper base plate

Test material  
20 x 20mm Cu plate

### Product Applications

## POWER DEVICES



\* Above data and photos are based on specific conditions